SN54HCT374, SN74HCT374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SCLS005D - MARCH 1984 - REVISED AUGUST 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current 3-State True Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 22 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible
- Eight D-Type Flip-Flops in a Single Package
- Full Parallel Access for Loading

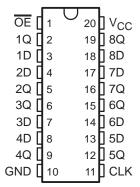
description/ordering information

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

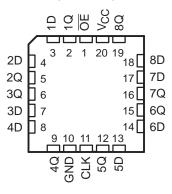
The eight flip-flops of the 'HCT374 devices are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels that were set up at the data (D) inputs.

An output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low

SN54HCT374 . . . J OR W PACKAGE SN74HCT374 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54HCT374 . . . FK PACKAGE (TOP VIEW)



logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

ORDERING INFORMATION

TA	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74HCT374N	SN74HCT374N
	2010 514	Tube of 25	SN74HCT374DW	1107074
	SOIC - DW	Reel of 2000	SN74HCT374DWR	HCT374
4000 1- 0500	SOP - NS	Reel of 2000	SN74HCT374NSR	HCT374
-40°C to 85°C	SSOP - DB	Reel of 2000 SN74HCT374DBI		HT374
	TSSOP – PW	Tube of 70	SN74HCT374PW	
		Reel of 2000	SN74HCT374PWR	HT374
		Reel of 250	SN74HCT374PWT	
	CDIP – J	Tube of 20	SNJ54HCT374J	SNJ54HCT374J
-55°C to 125°C	CFP – W	Tube of 85	SNJ54HCT374W	SNJ54HCT374W
	LCCC – FK	Tube of 55	SNJ54HCT374FK	SNJ54HCT374FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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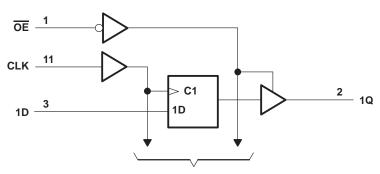
description/ordering information (continued)

OE does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

FUNCTION TABLE (each flip-flop)

	INPUTS	OUTPUT	
OE	CLK	D	Q
L	1	Н	Н
L	\uparrow	L	L
L	H or L	Χ	Q ₀
Н	Χ	Χ	Z

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see	ee Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CO}$	c) (see Note 1)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±35 mA
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ _{JA} (see Note 2):	: DB package	
-	DW package	58°C/W
	N package	
	NS package	60°C/W
	PW package	
Storage temperature range, T _{sto}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

				54HCT3	74	SN	74HCT3	74	LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V _{CC} = 4.5 V to 5.5 V	2			2			V
V _{IL}	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V			0.8			0.8	V
VI	Input voltage		0		Vcc	0		Vcc	V
VO	Output voltage		0		Vcc	0		Vcc	V
Δt/Δν	Input transition rise/fall time				500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		v _{cc}	Т	A = 25°C	;	SN54H	CT374	SN74HCT374		
PARAMETER				MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
V	Mr. Mr. andr.	I _{OH} = -20 μA	45.1/	4.4	4.499		4.4		4.4		.,
VOH	VI = VIH or VIL	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		V
.,		I _{OL} = 20 μA	4.5.1/		0.001	0.1		0.1		0.1	.,
V_{OL}	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	V
l _l	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0		5.5 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	5.5 V			8		160		80	μΑ
Δl _{CC} †	One input at 0.5 V Other inputs at 0 o		5.5 V		1.4	2.4		3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10		10	pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or VCC.

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V	$T_A = 1$	25°C	SN54H	CT374	SN74H	CT374	LINUT
		vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
,	Clock frequency	4.5 V		31		21		25	N 41 1-
†clock		5.5 V		36		23		28	MHz
	Pulse duration, CLK high or low	4.5 V	16		24		20		
t _W		5.5 V	14		22		18		ns
	Octor Concessor to the Concessor CLUC	4.5 V	20		30		25		
t _{su}	Setup time, data before CLK↑	5.5 V	17		27		23		ns
th	Hold time, data after CLK↑	4.5 V	10		10		10	·	ns
		5.5 V	10		10		10	·	



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switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

242445	FROM	то	,,	T,	ղ = 25°C	;	SN54H	CT374	SN74H	CT374		
PARAMETER	(INPUT)	(OUTPUT)	(OUTPUT) VCC		TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			4.5 V	31	36		21		25		NAL 1-	
f _{max}			5.5 V	36	40		23		28		MHz	
4 .	CLK	A O	4.5 V		30	36		54		45		
^t pd	CLK	Any Q	5.5 V		25	32		49		41	ns	
	<u>OE</u>		4.5 V		26	30		45		38		
t _{en}	OE	Any Q	5.5 V		23	27		41		34	ns	
	ŌĒ	A O	4.5 V		23	30		45		38		
^t dis	OE	Any Q	5.5 V		22	27		41		34	ns	
4.		Δην. Ο	4.5 V		10	12		18		15	20	
t _t		Any Q	5.5 V		9	11		16		14	ns	

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	TO (OUTPUT)	.,	T _A = 25°C		SN54HCT374		SN74HCT374			
PARAMETER	(INPUT)		VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	CLK		4.5 V		40	46		69		58	
^t pd		Any Q	5.5 V		35	41		62		52	ns
	ŌĒ	A O	4.5 V		34	40		60		50	
^t en		Any Q	5.5 V		29	36		54		45	ns
t _t		A-214 O	4.5 V		18	42		63		53	
		Any Q	Any Q	5.5 V		16	38		57		48

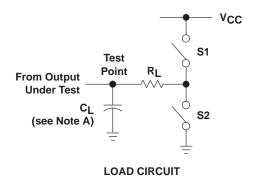
operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per flip-flop	No load	85	pF

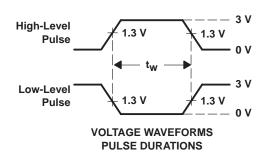


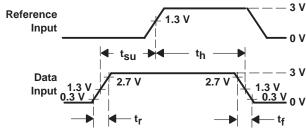
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PARAMETER MEASUREMENT INFORMATION

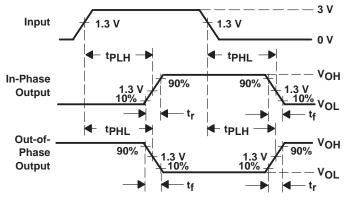


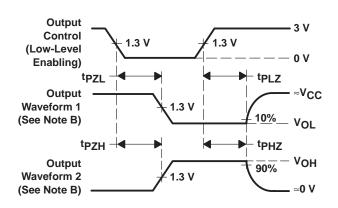
PARAM	PARAMETER		CL	S1	S2
	tPZH	1 kO	50 pF 1 kΩ or –		Closed
t _{en}	tPZL	1 K22	150 pF	Closed	Open
4	tPHZ	1 k Ω	50 pF	Open	Closed
^t dis	tPLZ	1 K22	50 pr	Closed	Open
t _{pd} or t _t			50 pF or 150 pF	Open	Open





VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT RISE AND FALL TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- D. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tp7I and tp7H are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



14 LEADS SHOWN

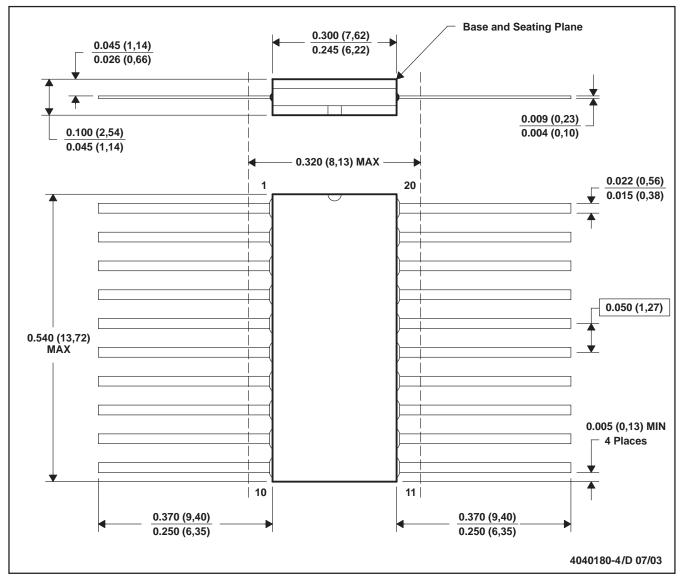


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



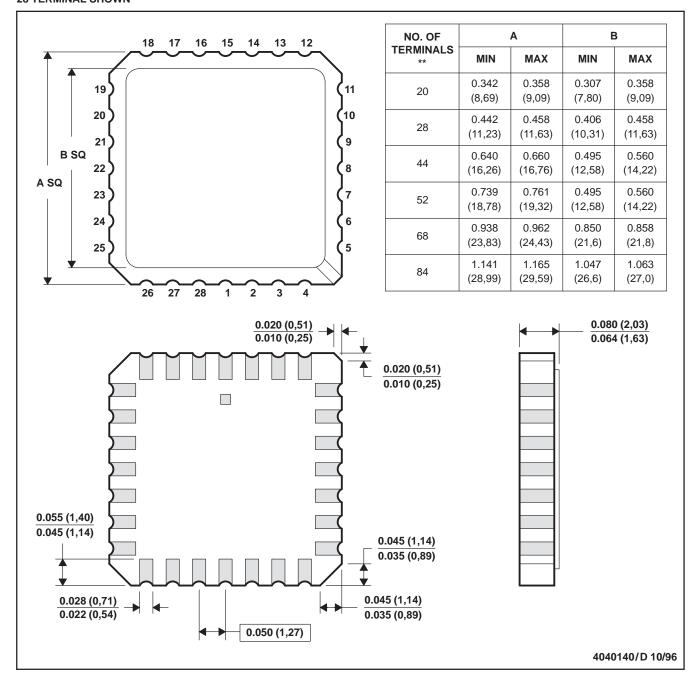
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



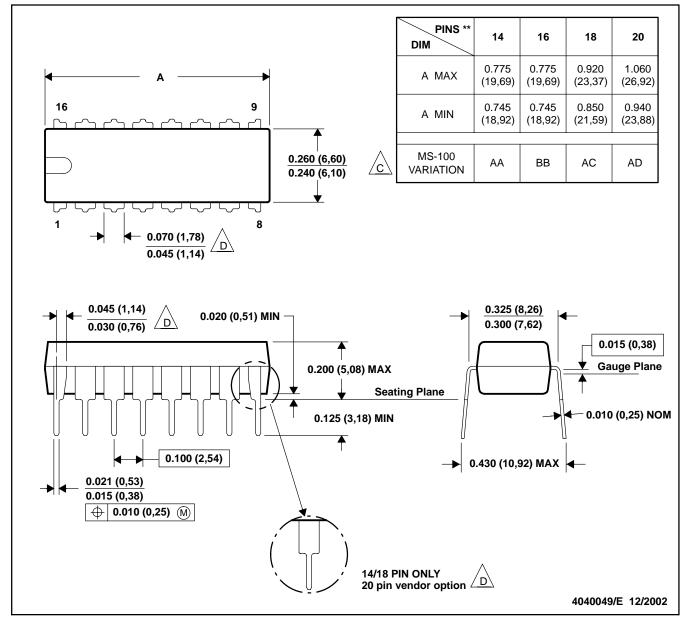
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

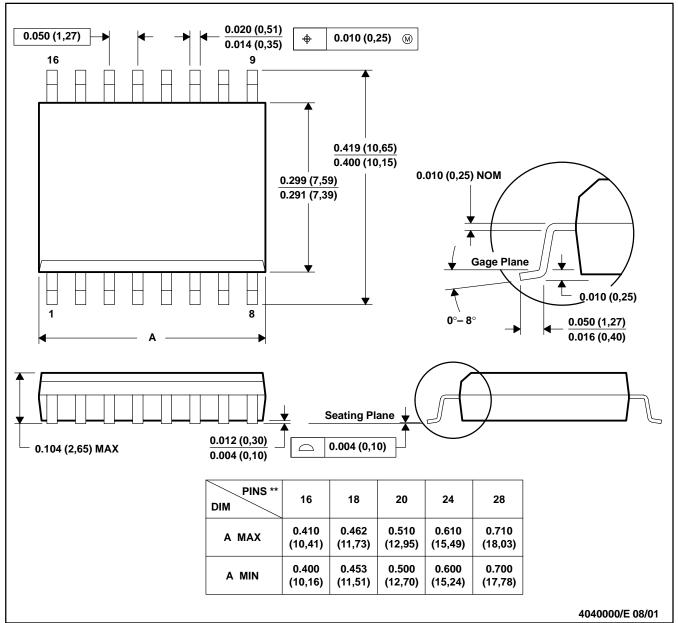
Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

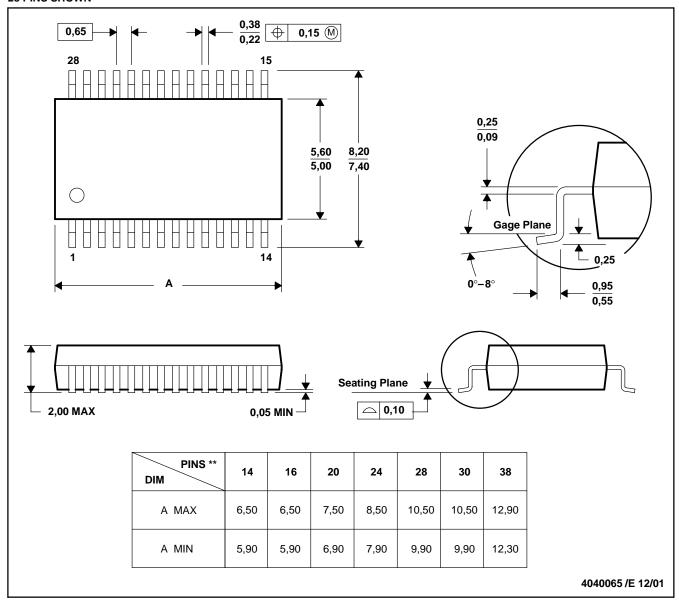
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

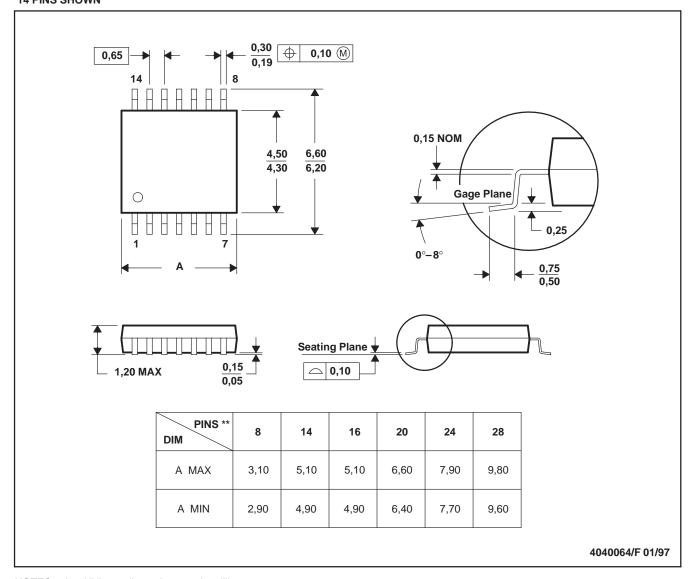
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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